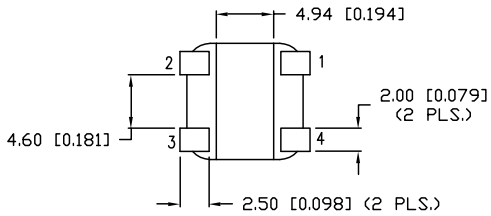
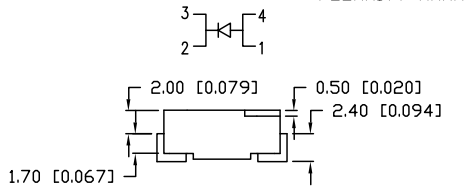
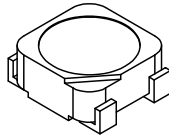
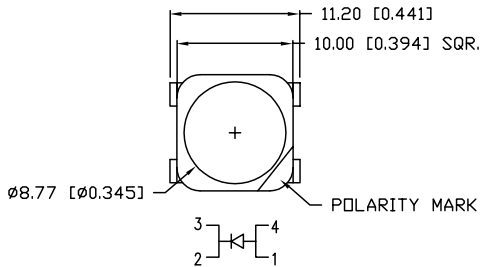
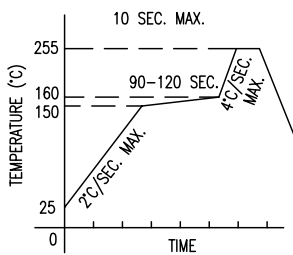


UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SML-LX1110SYC-ATR		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11440.	9.07.07



LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=350\text{mA}$

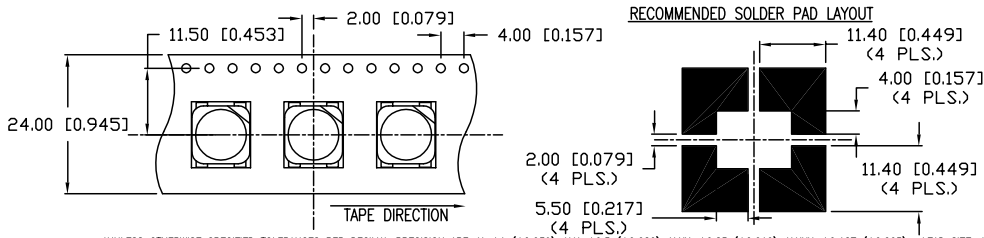
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		590		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		19000		mcd	$I_f=350\text{mA}$
LUMINOUS FLUX		20		lm	$I_f=350\text{mA}$
VIEWING ANGLE		90		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	500	mA
STEADY CURRENT	350	mA
POWER DISSIPATION	1.2	W
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-40 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

RECOMMENDED SOLDER PAD LAYOUT



NOTES:

- ANODE TOWARDS TAPE HOLE.



UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

REV. A	PART NUMBER SML-LX1110SYC-ATR	CONFIDENTIAL INFORMATION THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	LUMEX LUM. THE ONLY PROGRESS IS TO WORK FOR YOU	290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw
PLCC-4 SMT LED, HIGH POWER, 590nm SUPER YELLOW, WITH INTERNAL REFLECTIVE CAVITY.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: JD	CHECKED BY: APPROVED BY: DATE: 7.11.05 PAGE: 1 OF 1 SCALE: N/A